

/ Descriptions

GIQ3936 M M HVG 3 1 1
 DFN0603 Plastic Package ESD Protection Diode.

/ Features

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 i f β
 Ultra small package, Response Time is Typically < 1 ns, ESD > 30KV per Human Body Model,IEC6100042 Level 4 ESD Protection,HF Product.

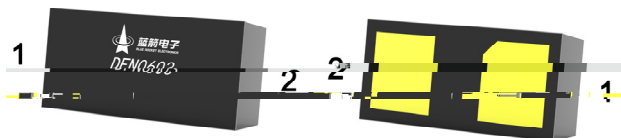
/ Applications

PS6 H Q H Q A A t V U 3 V t A
 Suitable for cellular phones audio,MP3 players, Digital cameras, Portable devices, mobile telephone and other users.

/ Equivalent Circuit



/ Pinning



/ Marking

M 1 " See Marking Instructions.

/ Absolute Maximum Ratings($T_a=25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Peak pulse power ($t_p = 8/20\mu\text{s}$)	P_K	69	W
Peak pulse current ($t_p = 8/20\mu\text{s}$)	I_{PP}	5.5	A
ESD according to IEC61000-4-2 air discharge	V_{ESD}	± 30	KV
ESD according to IEC61000-4-2 contact discharge		± 30	
Junction temperature	T_J	150	
Storage temperature	T_{STG}	-55~+150	

/ Electrical Characteristics($T_a=25^\circ\text{C}$)

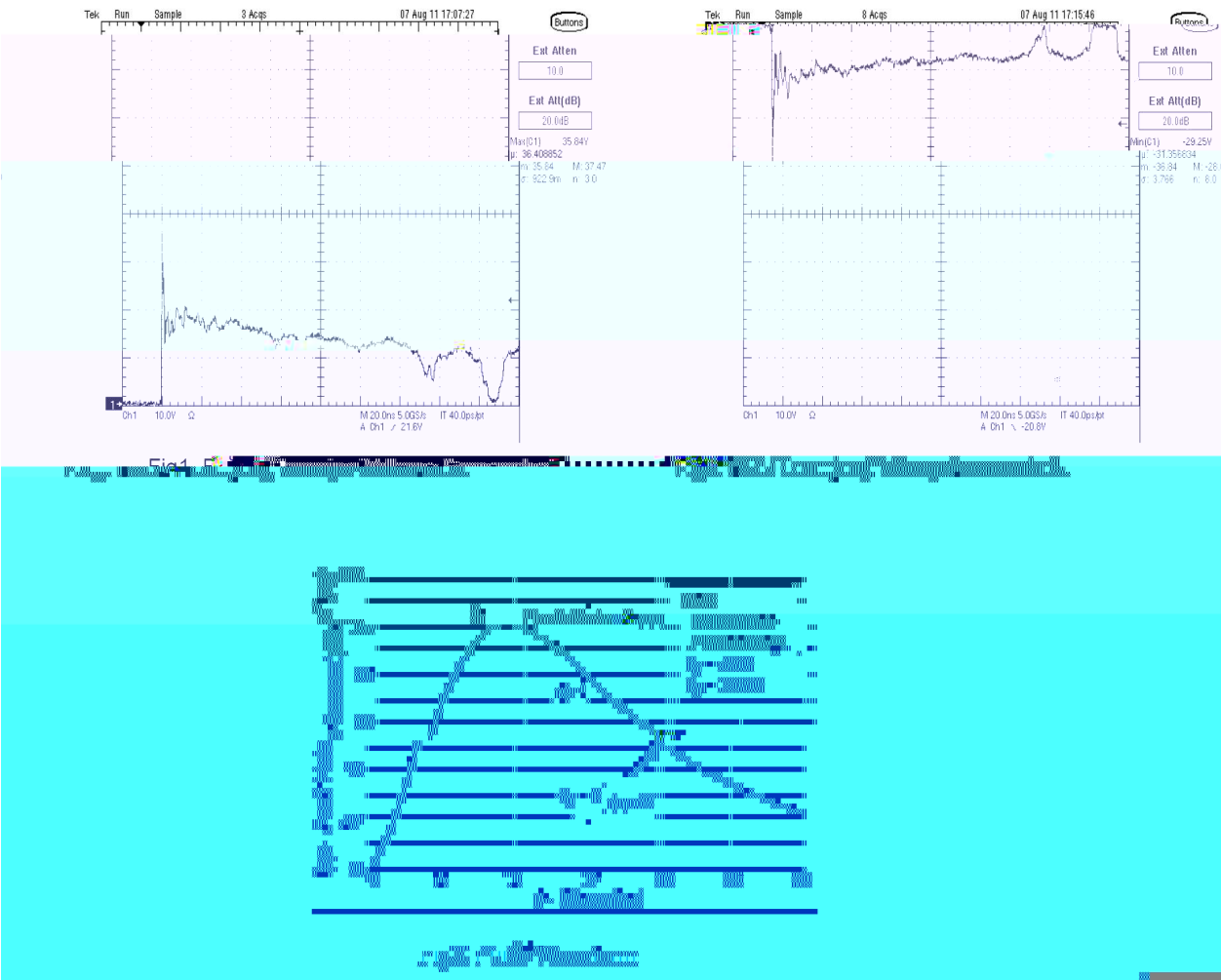
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse maximum working voltage	V_{RWM}				3.3	V
Reverse leakage current	I_R	$V_{RWM} = 3.3\text{V}$			0.1	μA
Reverse breakdown voltage ¹⁾	V_{BR}	$I_T = 1\text{mA}$	5.0		6.8	V
Clamping voltage ²⁾	V_C	$I_{PP} = 1\text{A}$ $t_p = 8/20\mu\text{s}$			9.8	V
		$I_{PP} = 5.5\text{A}$ $t_p = 8/20\mu\text{s}$			12.5	V
Junction capacitance	C_J	$V_R = 0\text{V}$ $f = 1\text{MHz}$			15	pF

Notes:

1) V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25°C .

2) Non-repetitive current pulse, according to IEC61000-4-5.

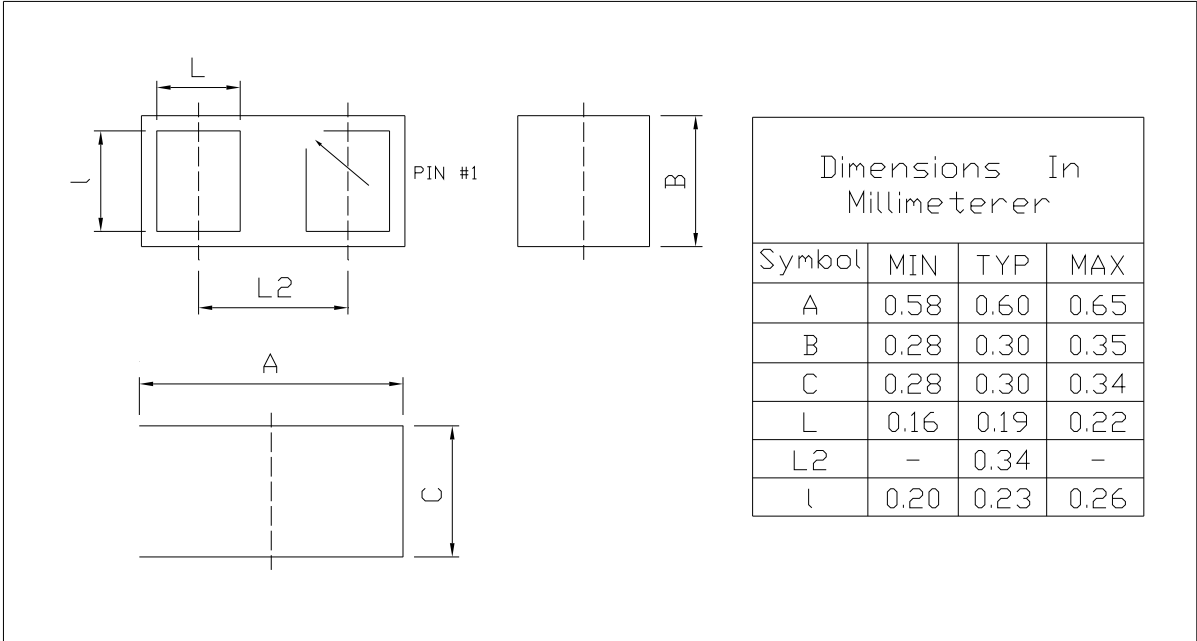
/ Electrical Characteristic Curve



/ Package Dimensions

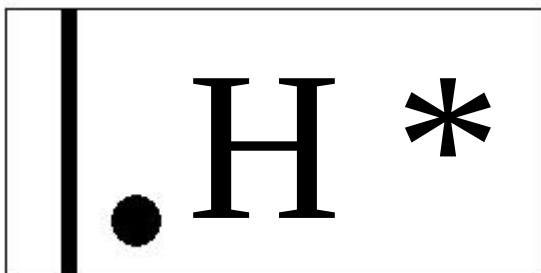
DFN0603

Unit:mm



Rev.02 202102

/ Marking Instructions



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*χ Lot No. Code,code change with Lot No


() / Temperature Profile for IR Reflow Soldering(Pb-Free)

” X

1 150~180 ℃ 60~90sec;

2 245±5 ℃ 5~0.5sec;

3 2~10 ℃/sec.

Note:

1.Preheating:150~180 ℃ , Time:60~90sec.

2.Peak Temp.:245±5 ℃ , Duration:5~0.5sec.

3. Cooling Speed: 2~10 ℃ /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 ℃ 10~15 sec